

## Three Phase Rectifier Bridge with Brake Chopper

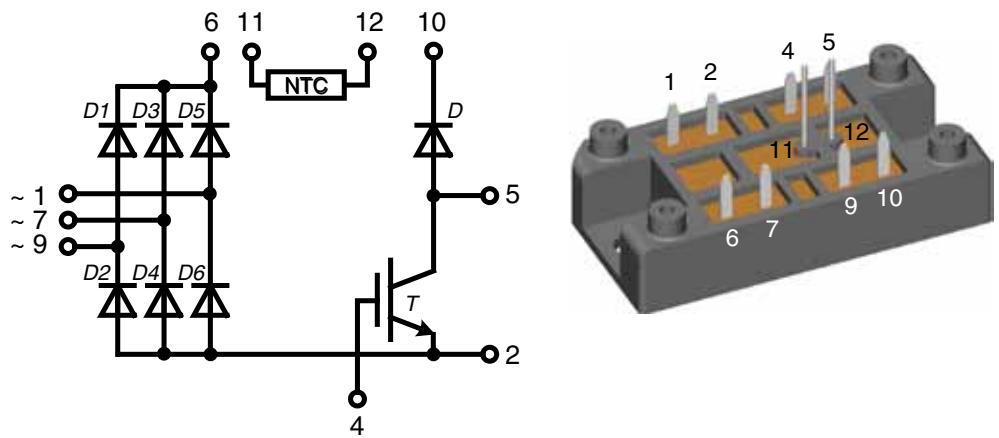
$V_{RRM} = 1200/1600 \text{ V}$

$I_{dAVM} = 110 \text{ A}$

**Part name** (Marking on product)

VUB72-12NOXT

VUB72-16NOXT



### Features:

- Three phase mains rectifier
- Brake chopper:
  - IGBT with low saturation voltage
  - HiPerFRED™ free wheeling diode

### Application:

- Drives with
  - mains input
  - DC link
  - inverter or chopper feeding the machine
  - motor and generator/brake operation

### Package:

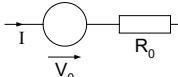
- High level of integration
- Solder terminals for PCB mounting
- UL pending, E72873
- Isolated DCB ceramic base plate
- Large creepage and strike distances
- High reliability

**Chopper IGBT T****Ratings**

<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$V_{CES}$	collector emitter voltage		$T_{VJ} = 25^\circ\text{C}$ to $150^\circ\text{C}$		1200	V
$V_{GES}$	max. DC gate voltage	continuous	-20		+20	V
$I_{C25}$	collector current	DC	$T_C = 25^\circ\text{C}$		58	A
$I_{C80}$		DC	$T_C = 80^\circ\text{C}$		40	A
$V_{CE(\text{sat})}$	collector emitter saturation voltage	$I_C = 35 \text{ A}; V_{GE} = 15 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.85 2.15	2.2	V
$V_{GE(\text{th})}$	gate emitter threshold voltage	$I_C = 1 \text{ mA}$	$T_{VJ} = 25^\circ\text{C}$	5.4	6.5	V
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.1	0.1	mA mA
$I_{GES}$	gate emitter leakage current	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			500	nA
$t_{d(on)}$	turn-on delay time	$V_{CE} = 600 \text{ V}; I_C = 35 \text{ A}$ $V_{GE} = \pm 15 \text{ V}; R_G = 27 \Omega; L = 100 \mu\text{H}$		70		ns
$t_r$	current rise time			40		ns
$t_{d(off)}$	turn-off delay time			250		ns
$t_f$	current fall time			100		ns
$E_{on}$	turn-on energy per pulse			3.8		mJ
$E_{off}$	turn-off energy per pulse			4.1		mJ
$Q_{Gon}$		$V_{CE} = 600 \text{ V}; V_{GE} = 15 \text{ V}; I_C = 35 \text{ A}$		110		nC
$I_{CM}$	reverse bias safe operating area	$RBSOA; V_{GE} = \pm 15 \text{ V}; R_G = 27 \Omega; L = 100 \mu\text{H}$		70		A
$V_{CEK}$		clamped inductive load;	$T_{VJ} = 125^\circ\text{C}$	$\leq V_{CES} \cdot L_s \cdot d_i / dt$		V
$t_{sc}$ (SCSOA)	short circuit safe operating area	$V_{CE} = 900 \text{ V}; V_{GE} = \pm 15 \text{ V}; R_G = 27 \Omega$ ; non-repetitive	$T_{VJ} = 125^\circ\text{C}$		10	$\mu\text{s}$
$R_{thJC}$	thermal resistance junction to case				0.65	K/W
$R_{thCH}$	thermal resistance case to heatsink	with heat transfer paste, see mounting instructions			0.9	K/W

**Chopper Diode D****Ratings**

<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$V_{RRM}$	max. repetitive reverse voltage		$T_{VJ} = 150^\circ\text{C}$		1200	V
$I_{F25}$	forward current	DC	$T_C = 25^\circ\text{C}$		25	A
$I_{F80}$			$T_C = 125^\circ\text{C}$		15	A
$V_F$	forward voltage	$I_F = 25 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.7 2.0	3.1	V
$I_R$	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.1	0.1	mA mA
$I_{RM}$	reverse recovery current	$I_F = 15 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 125^\circ\text{C}$	16		A
$t_{rr}$	reverse recovery time	$di_F/dt = -400 \text{ A}/\mu\text{s}$		130		ns
$R_{thJC}$	thermal resistance junction to case				2.3	K/W
$R_{thJH}$	thermal resistance case to heatsink	with heat transfer paste			3.12	K/W

**Equivalent Circuits for Simulation****Ratings**

<b>Symbol</b>	<b>Definitions</b>	<b>Conditions</b>	<b>min.</b>	<b>typ.</b>	<b>max.</b>	<b>Unit</b>
$V_0$	Diode	D1 - D6	$T_{VJ} = 125^\circ\text{C}$	0.85		V
$R_0$				7		$\text{m}\Omega$
$V_0$	IGBT	T	$T_{VJ} = 150^\circ\text{C}$	1.1		V
$R_0$				40		$\text{m}\Omega$
$V_0$	Diode	D	$T_{VJ} = 125^\circ\text{C}$	1.25		V
$R_0$				32		$\text{m}\Omega$

IXYS reserves the right to change limits, test conditions and dimensions.

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**Input Rectifier Diode D1 - D6**

Symbol	Conditions	Ratings			
		min.	typ.	max.	
$V_{RRM}$	max. repetitive reverse voltage	VUB 72 -12 NO1 VUB 72 -16 NO1	$T_{VJ} = 25^\circ\text{C}$	1200 1600	V V
$I_{FAV}$	average forward current	sine 180°	$T_C = 80^\circ\text{C}$	40	A
$I_{D(AV)M}$	max. average DC output current	rectangular; $d = 1/3$ ; bridge	$T_C = 80^\circ\text{C}$	110	A
$I_{FSM}$	max. surge forward current	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$	530	A
$P_{tot}$	total power dissipation		$T_C = 25^\circ\text{C}$	100	W
$I_R$	reverse current	$V_R = V_{RRM}$ $V_R = 0.8 \cdot V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.02 0.4	mA mA
$V_F$	forward voltage	$I_F = 25 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.0 0.9	V V
$R_{thJC}$	thermal resistance junction to case	per diode	$T_{VJ} = 25^\circ\text{C}$	1.2	K/W
$R_{thJH}$	thermal resistance case to heatsink	with heat transfer paste	$T_{VJ} = 25^\circ\text{C}$	1.42	K/W

**Temperature Sensor NTC**

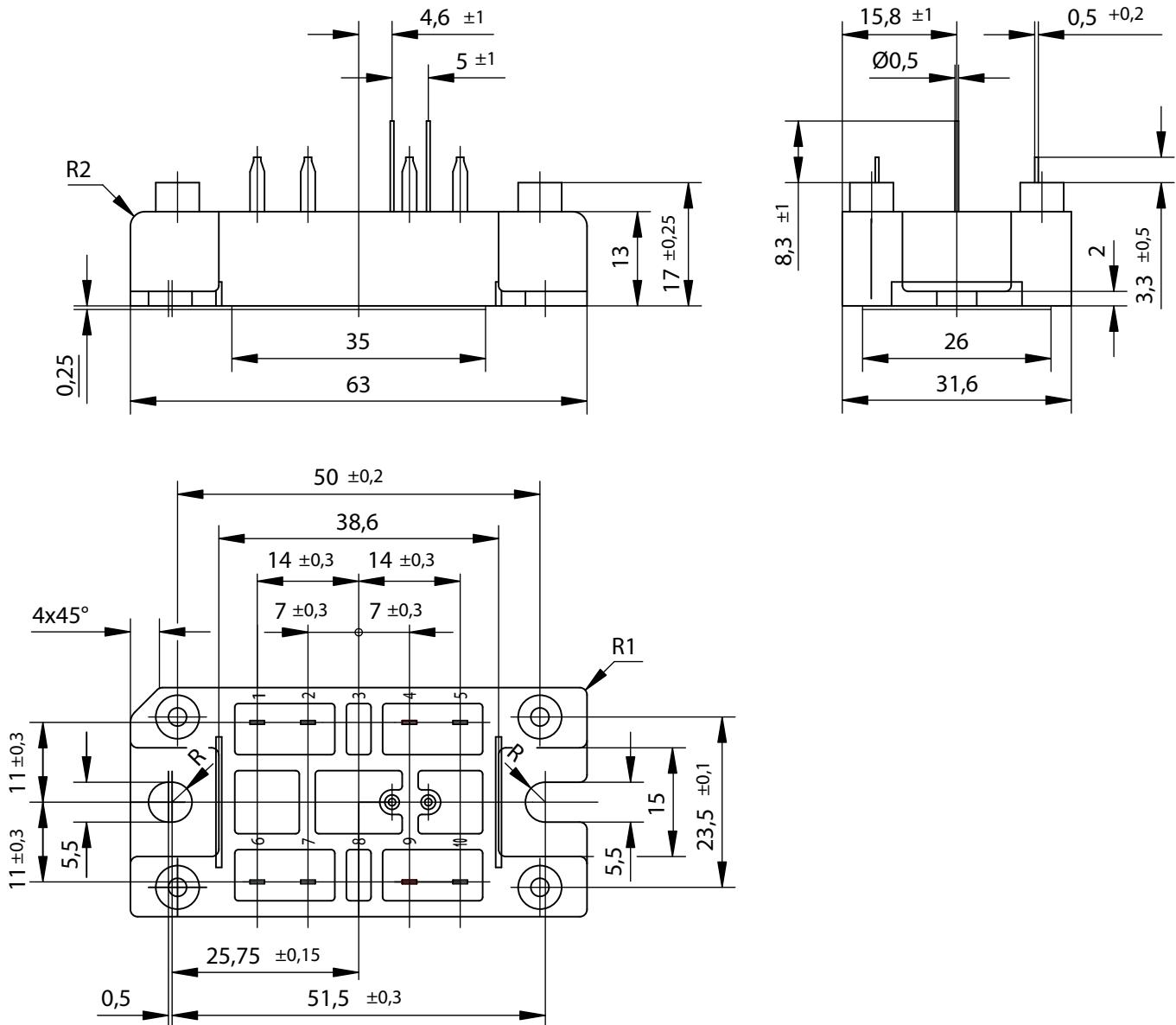
Ratings				
Symbol	Definitions	Conditions	min.	typ.
$R_{25}$ $B_{25/100}$	resistance	$\{ R(T) = R_{25} \cdot e^{B_{25/100} \left[ \frac{1}{T} - \frac{1}{298K} \right]} \}$	$T = 25^\circ\text{C}$	2.2 3560

**Module**

Ratings				
Symbol	Definitions	Conditions	min.	typ.
$I_{RMS}$	RMS current	per pin		100
$T_{VJ}$	operating temperature		-40	150
$T_{VJM}$	max. virtual junction temperature			150
$T_{stg}$	storage temperature		-40	125
$V_{ISOL}$	isolation voltage	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz};$ $t = 1 \text{ min}$		3600
$M_d$	mounting torque	(M5)	2	2.5
$d_s$	creep distance on surface		5	
$d_A$	strike distance through air		5	
<b>Weight</b>			35	g

## Outline Drawing

Dimensions in mm (1 mm = 0.0394")



## Product Marking

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	VUB 72-12NOXT	VUB72-12NOXT	Box	10	510734
Standard	VUB 72-16NOXT	VUB72-16NOXT	Box	10	510741

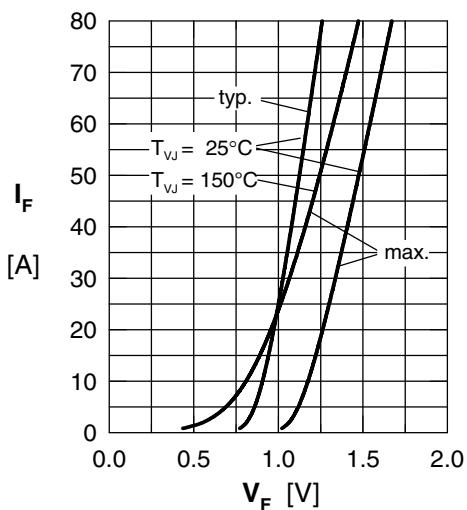


Fig. 1 Forward current vs. voltage drop per rectifier diode

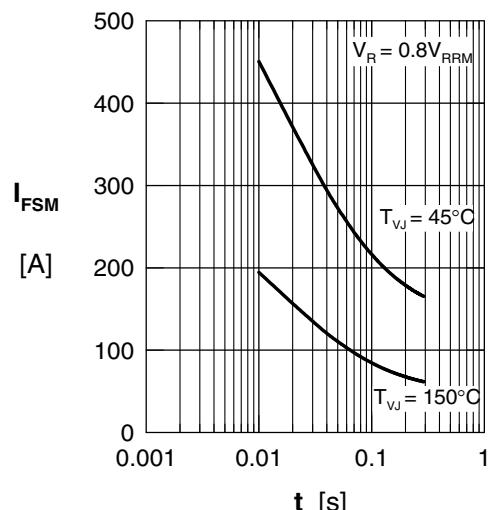


Fig. 2 Surge overload current per rectifier diode

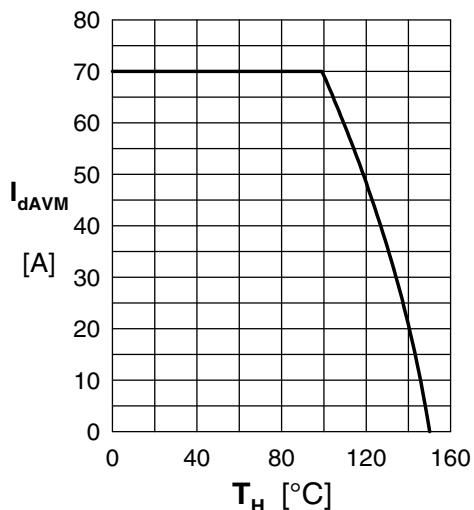


Fig. 3 Max. forward current vs. heatsink temperature (Rectifier bridge)

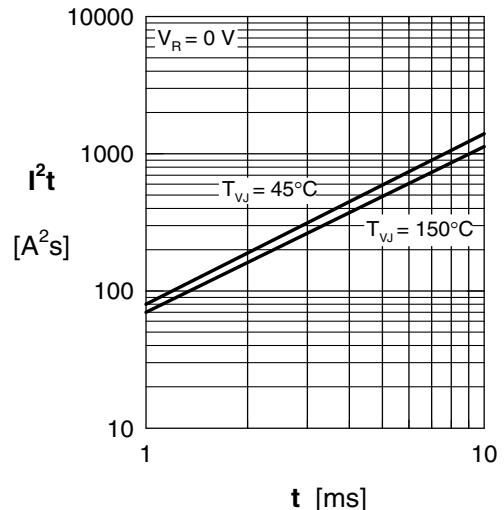


Fig. 4  $I^2t$  versus time per rectifier diode

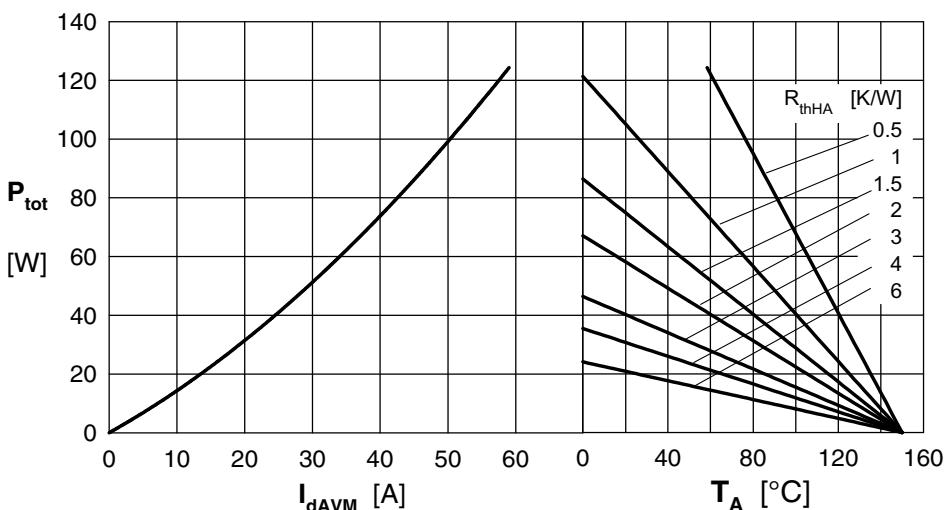


Fig. 5 Power dissipation vs. direct output current & ambient temperature (Rectifier bridge)

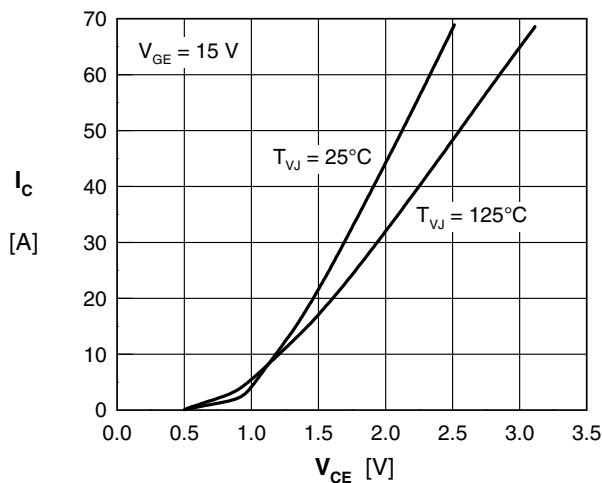


Fig. 6 IGBT, typ. output characteristics

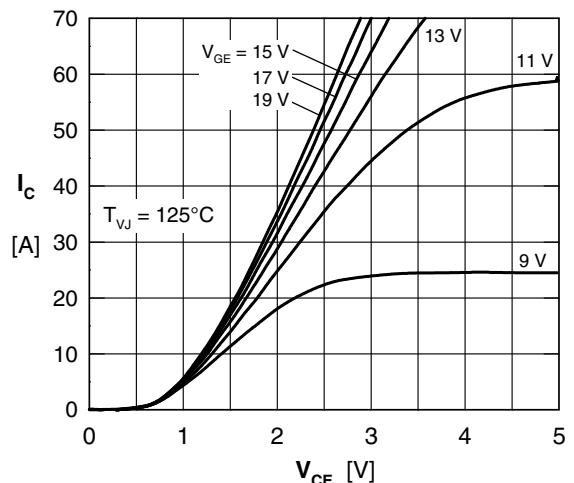


Fig. 7 IGBT, typ. output characteristics

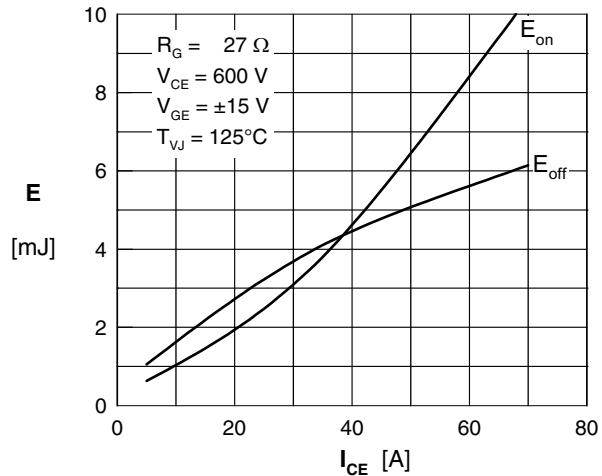


Fig. 8 IGBT, typ. switching energy versus collector current

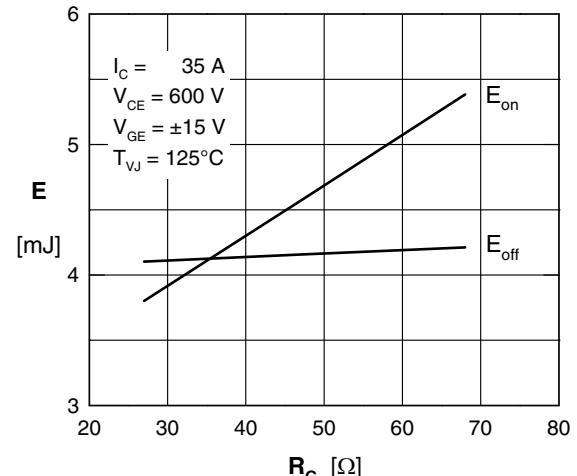


Fig. 9 IGBT, typ. switching energy versus gate resistance

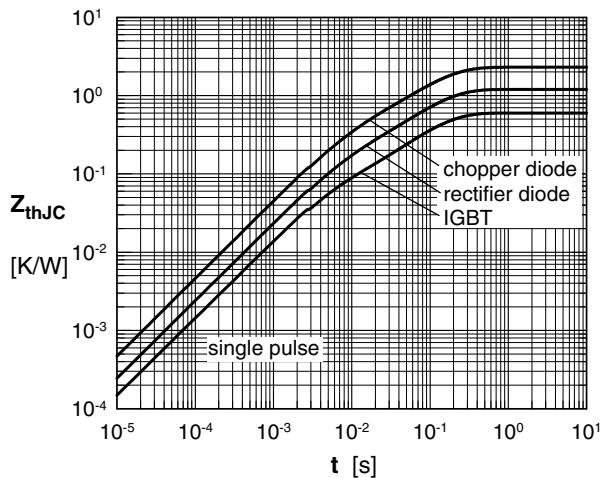


Fig. 10 Typ. transient thermal impedance

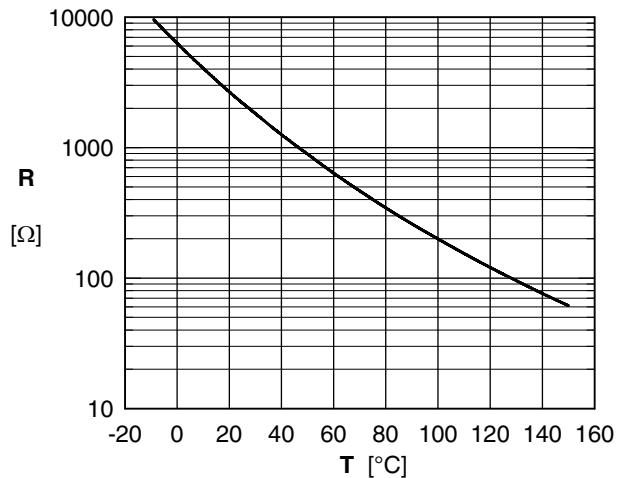


Fig. 11 Typ. thermistor resistace vs. temperature

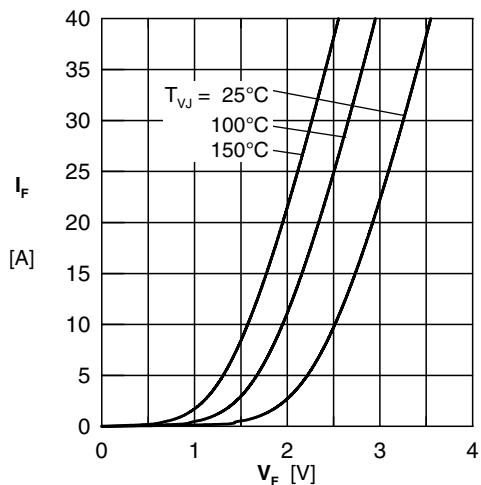


Fig. 12 Forward current  $I_F$  versus  $V_F$

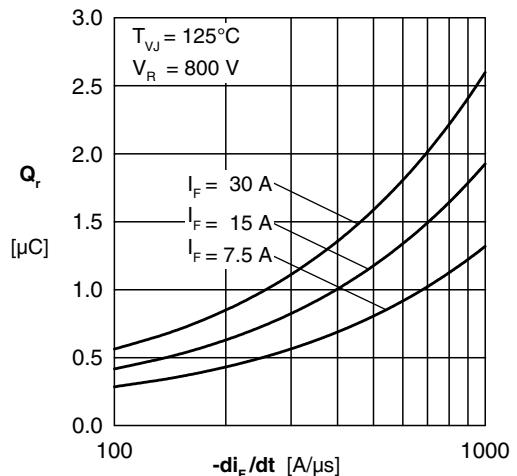


Fig. 13 Typ. reverse recovery charge  $Q_r$  versus  $-di_F/dt$

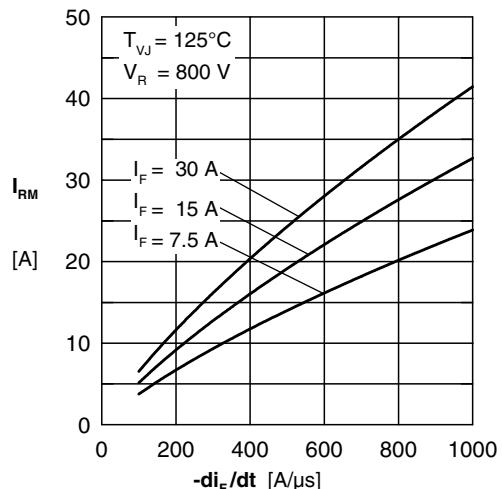


Fig. 14 Typ. peak reverse current  $I_{RM}$  versus  $-di_F/dt$

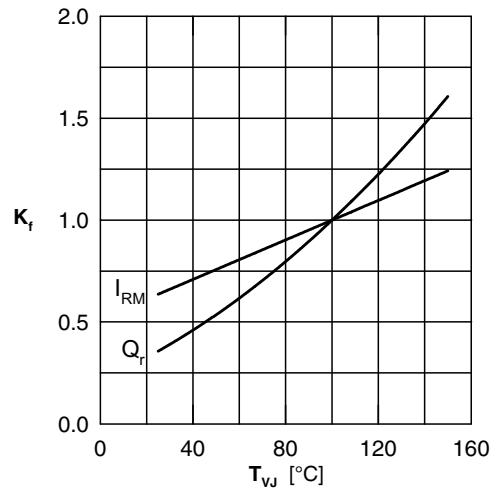


Fig. 15 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus  $T_{VJ}$

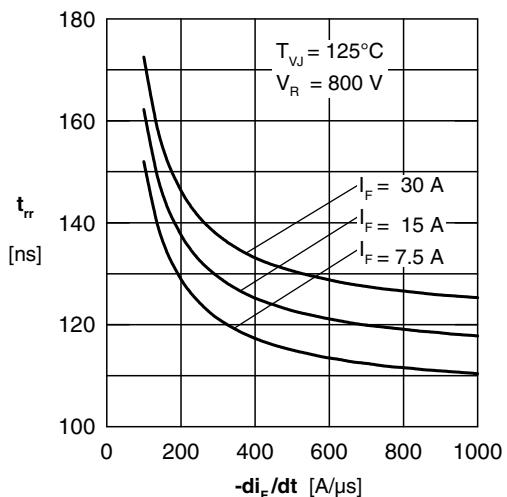


Fig. 16 Typ. recovery time  $t_{rr}$  versus  $-di_F/dt$

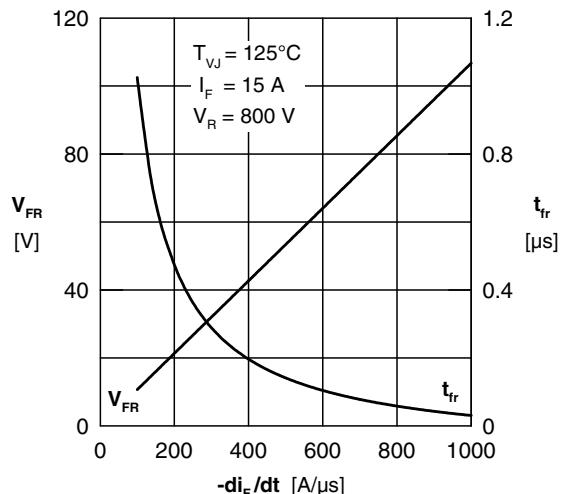


Fig. 17 Typ. peak forward voltage  $V_{FR}$  and  $t_{fr}$  versus  $di_F/dt$